

SOT1573-1

HQFN16, plastic, thermal enhanced quad flat package; no leads; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.98 mm body

1 July 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN16
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	19-06-2020
Manufacturer package code	98ASA00893D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
package height	1.88	1.98	2.08	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

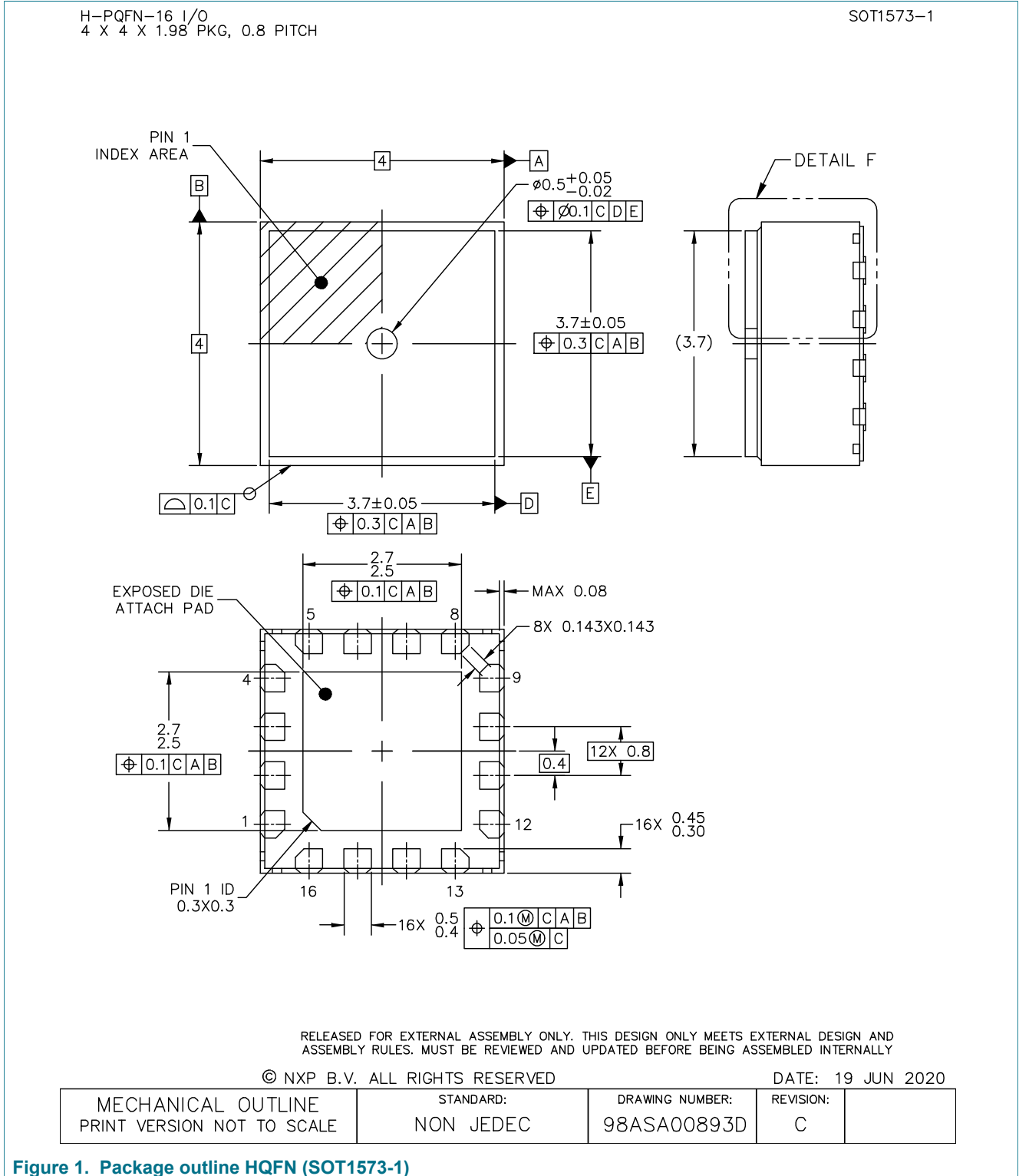
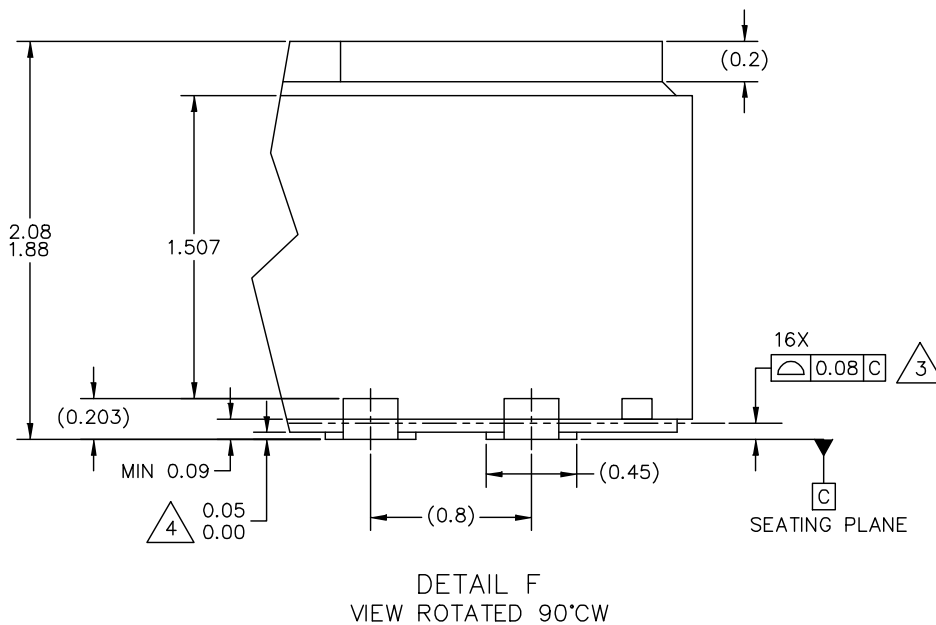


Figure 1. Package outline HQFN (SOT1573-1)

HQFN16, plastic, thermal enhanced quad flat package; no leads; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.98 mm body

H-PQFN-16 I/O
4 X 4 X 1.98 PKG, 0.8 PITCH

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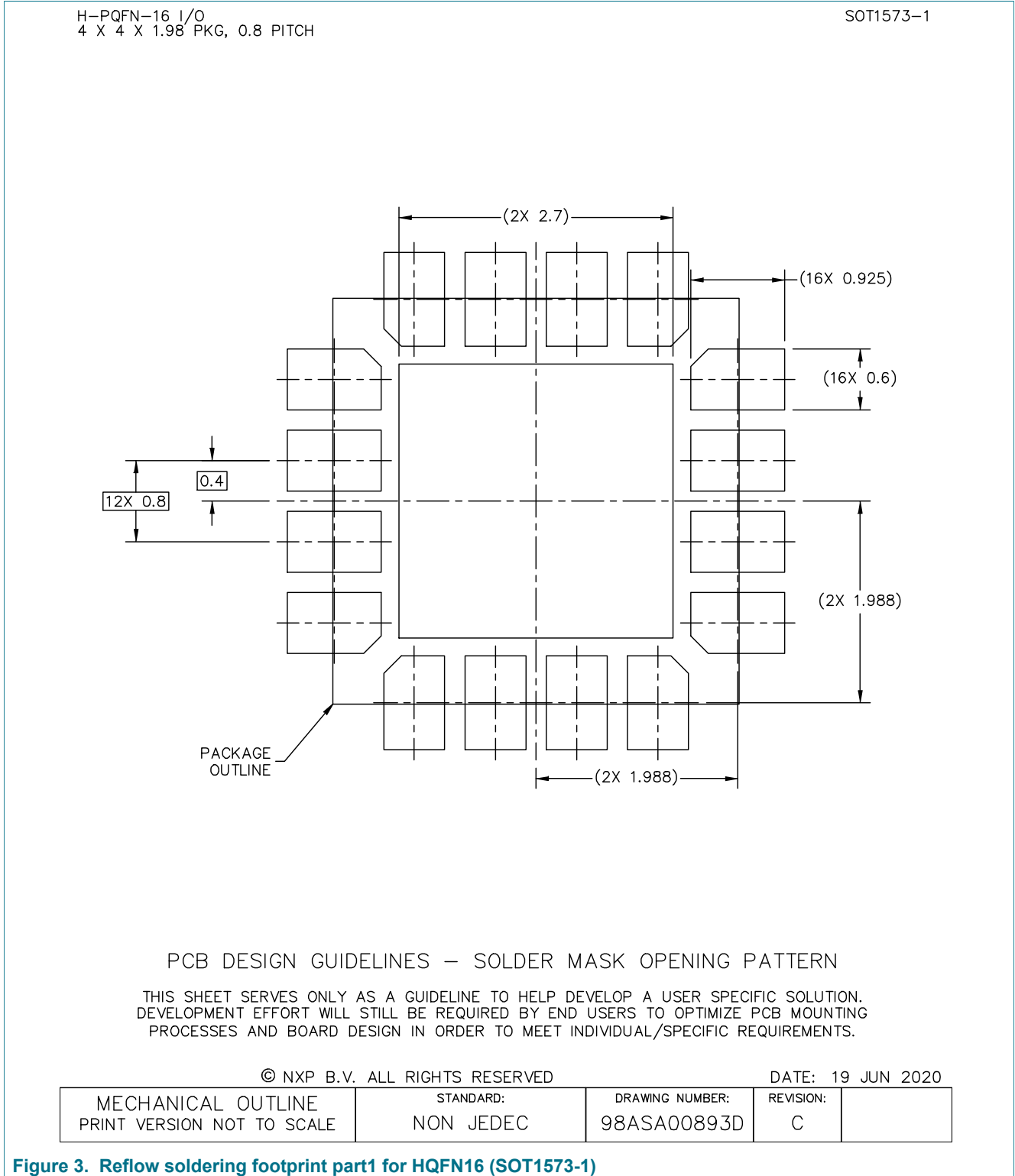
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Figure 2. Package outline dt1 HQFN (SOT1573-1)

HQFN16, plastic, thermal enhanced quad flat package; no leads; 16 terminals; 0.8 mm pitch; 4 mm x 4 mm x 1.98 mm body

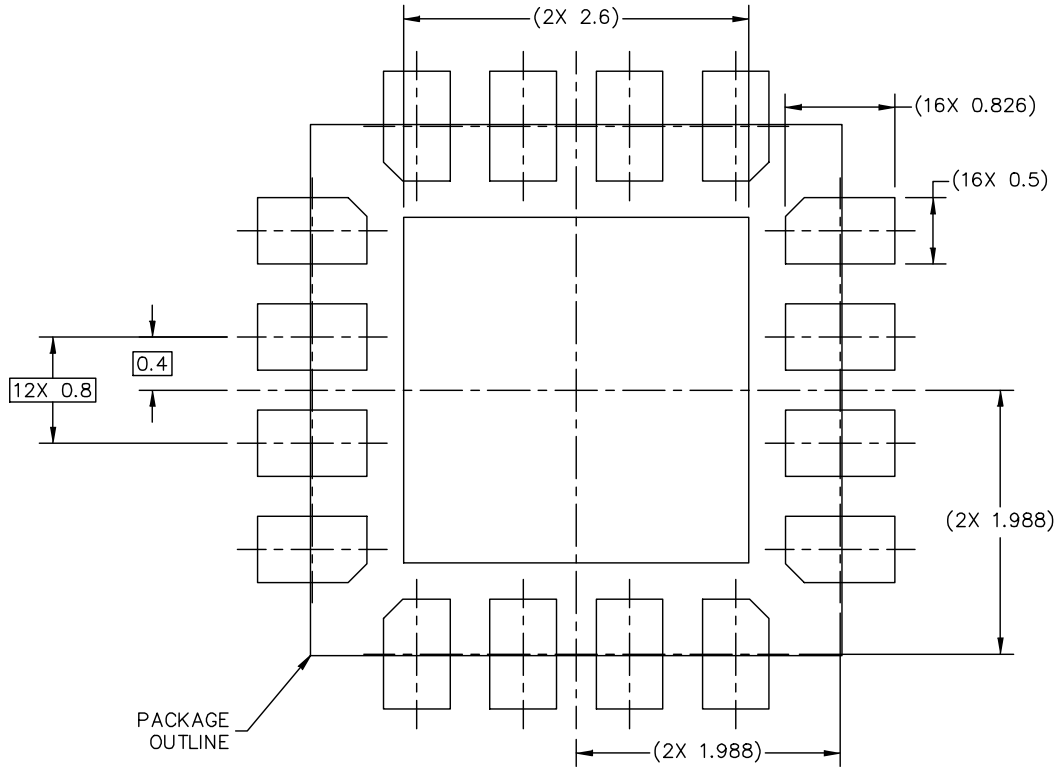
3 Soldering



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SOT1573-1



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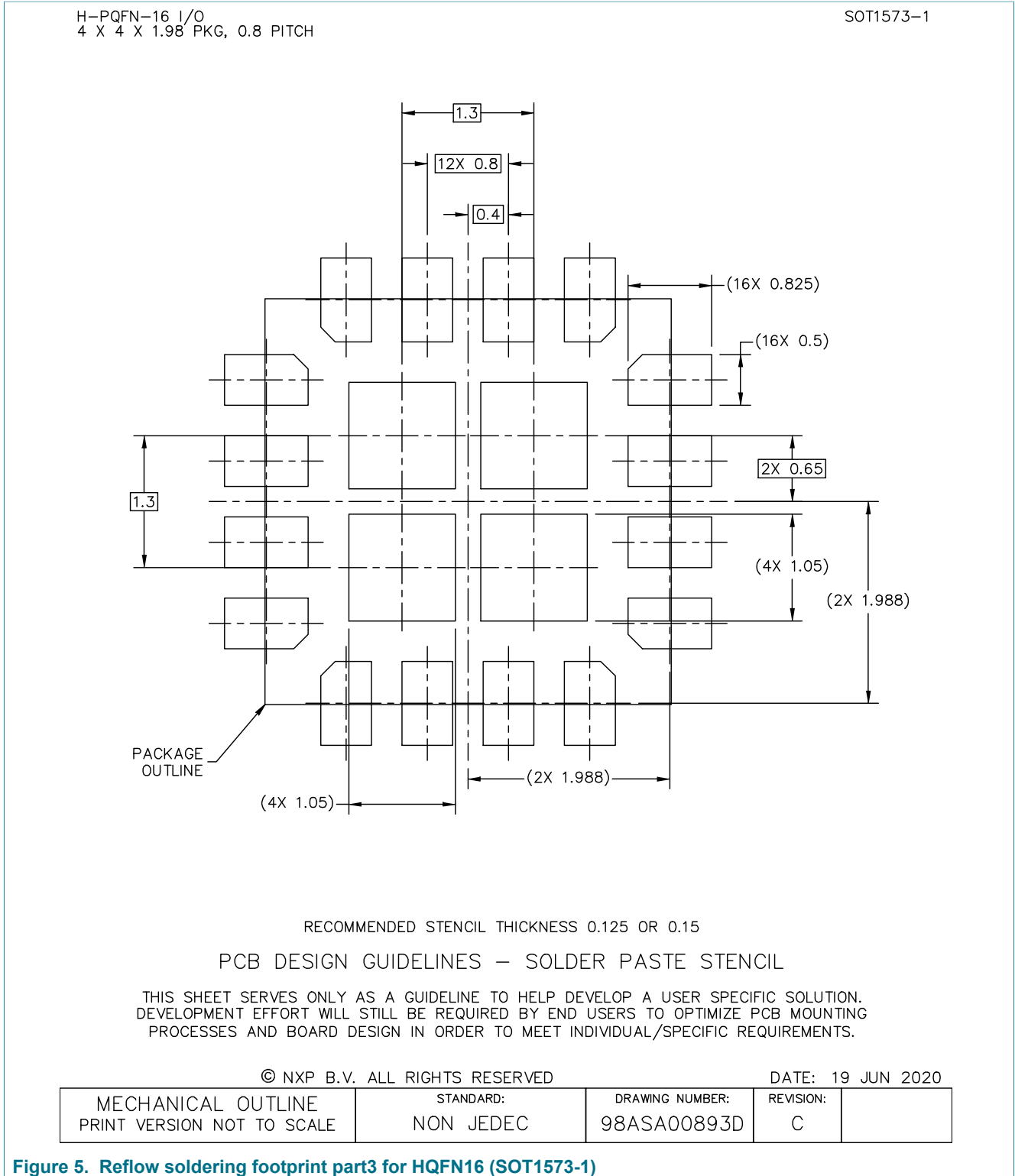
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Figure 4. Reflow soldering footprint part2 for HQFN16 (SOT1573-1)

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
4. DIMENSION APPLIES ONLY FOR TERMINALS.
5. MIN METAL GAP SHOULD BE 0.2 MM.

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Figure 6. Package outline note HQFN (SOT1573-1)

4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering4
4 Legal information8